

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	8230	((257/527,594,618,622) or (438/33,68,107,113,460-465)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 13:38
S4	6947	S2 and ((@ad<"20040319") or (@rlad<"20040319"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:38
S5	4288	S4 and first and second	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:38
S6	2278	(257/527,594,618,622).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 14:05
S7	1891	S6 and ((@ad<"20040319") or (@rlad<"20040319"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:43
S8	1070	S7 and (first and second)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:38
S9	319	S7 and (first and second and third and fourth)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:27

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S10	18661	wafer near3 dic\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:42
S11	23256	(substrate wafer) near3 dic\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:42
S12	5354	S11 and (first and second and third and fourth)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:43
S13	4477	S12 and ((@ad<"20040319") or (@rlad<"20040319"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:43
S18	667	lattice and S2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 21:58
S19	204	stagger\$3 near3 lattice	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 22:04
S20	1	S2 and stagger\$3 near3 lattice	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 22:05

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S21	127	S2 and stagger\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 14:23
S22	5565	((257/620,622,) or (438/110,113,460,462,977,FOR386)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/14 22:12
S23	4527	((257/620,622,) or (438/110,113,460,462,977,FOR386)).CCLS.	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/14 22:16
S26	13	S2 and stagge\$3 near3 (street scrib\$3 lattice pattern)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/14 22:31
S27	8230	((257/527,594,618,622) or (438/33,68,107,113,460-465)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 13:43
S28	0	S27 and stagger near3 lattice and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 13:43
S29	0	S27 and stagger near3 lattice and (wafer substrate semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 13:43

EAST Search History

S30	1	S27 and stagger\$3 near3 lattice and (wafer substrate semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 17:09
S31	8230	((257/527,594,618,622) or (438/33, 68,107,113,460-465)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 17:08
S32	166493	6and stagger\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 14:23
S33	127	S31 and stagger\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 14:24
S34	130	S31 and (cut\$3 saw\$3 dic\$3) with (horizont\$3 logitud\$3) and (cut\$3 saw\$3 dic\$3) with (vertica\$3 latitud\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 14:35
S35	25	stager\$3 near10 (cut\$3 saw\$3 dic\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 14:59
S36	1015	257/620	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:27

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S37	939	S36 AND (saw\$3 dic\$2 cut\$3 pattern\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:28
S38	857	S37 and ((@ad<"20040319") or (@rlad<"20040319"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:50
S39	13587	((257/48,355,758,/773,774,620) or (438/401,462)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 16:54
S41	0	stragger\$3 near10 (dic\$3 cut\$3 pattern\$3 lattice)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:55
S42	100210	(zig\$3 stragger\$3 align\$3)near10 (dic\$3 cut\$3 pattern\$3 lattice)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:56
S43	38220	S42 and (wafer substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:56
S44	5735	S43 and (wafer substraee) with (zig\$3 stragger\$3 align\$3)near10 (dic\$3 cut\$3 pattern\$3 lattice)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 16:57

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S45	2826	S44 and (die chip)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 17:00
S46	16	S45 and (first and second and third and fourth and fifth) with (strip die chip)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 17:01
S47	1129	(438/460).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 17:09
S48	11	S47 and (stagger\$3 zig\$3 mis near3 align\$3) with (cut\$3 dic\$3 saw\$3 pattern\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 17:11
S49	1205	(438/113).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/15 17:11
S50	10	S49 and (stagger\$3 zig\$3 mis near3 align\$3) with (cut\$3 dic\$3 saw\$3 pattern\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/15 17:12